ICS 31.180 SLOVENSKÁ TECHNICKÁ NORMA December 2015

STN	**Skúšobné metódy pre elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy. Časť 2-721: Skúšobné metódy pre materiály na spájacie štruktúry. Meranie relatívnej permitivity a činiteľa dielektrických strát meďou plátovaného laminátu pri mikrovlnnej frekvencii dielektrického rezonátora.**	**STN EN 61189-2-721** 34 6513

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-721: Test methods for materials for interconnection structures - Measurement of relative permittivity and loss tangent for copper clad laminate at microwave frequency using split post dielectric resonator

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/15

Obsahuje: EN 61189-2-721:2015, IEC 61189-2-721:2015

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 61189-2-721

June 2015

ICS 31.180

English Version

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-721: Test methods for materials for interconnection structures - Measurement of relative permittivity and loss tangent for copper clad laminate at microwave frequency using split post dielectric resonator (IEC 61189-2-721:2015)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-721: Méthodes d'essai des matériaux pour structures d'interconnexion - Mesure de la permittivité relative et de la tangente de perte pour les stratifiés recouverts de cuivre en hyperfréquences à l'aide d'un résonateur diélectrique en anneaux fendus (IEC 61189-2-721:2015)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-721: Prüfverfahren für Verbindungsstrukturen (Leiterplatten) - Messung der relativen Permittivität und des Verlustfaktors von kupferkaschiertem Laminat im Mikrowellen-Frequenzbereich unter Verwendung eines Split Post dielektrischen Resonators (IEC 61189-2-721:2015)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

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European foreword

The text of document 91/1246/FDIS, future edition 1 of IEC 61189-2-721, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-2-721:2015.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2016-03-03
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IEC 61189-2-721

Edition 1.0 2015-04

INTERNATIONAL STANDARD

NORME INTERNATIONALE

colour inside

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IEC 61189-2-721:2015-04(en-fr)

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CONTENTS

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-721: Test methods for materials for interconnection structures – Measurement of relative permittivity and loss tangent for copper clad laminate at microwave frequency using split post dielectric resonator

FOREWORD

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The text of this standard is based on the following documents:

FDIS	Report on voting
91/1246/FDIS	91/1258/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-721: Test methods for materials for interconnection structures – Measurement of relative permittivity and loss tangent for copper clad laminate at microwave frequency using split post dielectric resonator

1 Scope

This part of IEC 61189 outlines a way to determine the relative permittivity (ε_r) and loss tangent (tanδ) (also called dielectric constant (*Dk)* and dissipation factor (*Df)*) of copper clad laminates at microwave frequencies (from 1,1 GHz to 20 GHz) using a split post dielectric resonator (SPDR).

This part of IEC 61189 is applicable to copper clad laminates and dielectric base materials.